

Description

The SFT1443-TL-W uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.



TO-252-2L

General Features

V_{DS} =100V,I_D =15A

 $R_{DS(ON)}$ <112m Ω @ V $_{GS}$ =10V

PIN1 G PIN3 S

Application

Power switch

DC/DC converters

N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SFT1443-TL-W	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Symbol	Parameter	Rating	Units	
Vos	Drain-Source Voltage	100	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	V ¹ 7.7		
Ірм	Pulsed Drain Current ²	24	А	
EAS	Single Pulse Avalanche Energy³	6.1	mJ	
las	Avalanche Current	11	А	
P _D @T _C =25°C	Total Power Dissipation ³	34.7	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
ReJA	Thermal Resistance Junction-ambient ¹	62	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	3.6 °C/W		

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVpss	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V	
△BV _{DSS} /△T _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA		0.098		V/°C	
_		V _{GS} =10V , I _D =10A		100	112	mΩ	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =8A		117	130	mΩ	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0		2.5	V	
$\triangle V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient			-4.57		mV/°C	
		V _{DS} =80V , V _{GS} =0V , T _J =25°C	1		1		
loss	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55°C			5	- uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		13		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2		Ω	
Qg	Total Gate Charge (10V)			26.2			
Qgs	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =10A		4.6		nC	
Qgd	Gate-Drain Charge			5.1			
Td(on)	Turn-On Delay Time			4.2			
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		8.2		ns	
Td(off)	Turn-Off Delay Time	R _G =3.3 I _D =10A		35.6			
Tf	Fall Time			9.6			
Ciss	Input Capacitance			1535			
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		60		pF	
Crss	Reverse Transfer Capacitance			37			
ls	Continuous Source Current ^{1,5}				12	Α	
lsм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			24	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
trr	Reverse Recovery Time	I- 40A II/I/ 400A/		37		nS	
Qrr	Reverse Recovery Charge	IF=10A,dl/dt=100A/μs , T _J =25°C		27.3		nC	

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300 us$, duty cycle $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1 mH, I_{AS}=11A$
- 4. The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

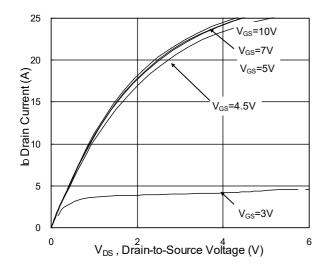


Fig.1 Typical Output Characteristics

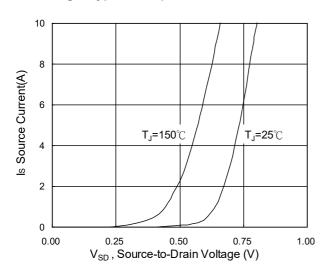


Fig.3 Forward Characteristics Of Reverse

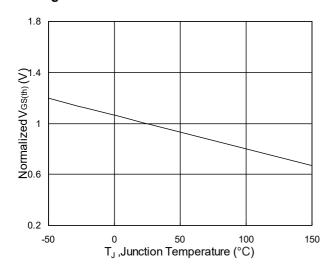


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_J

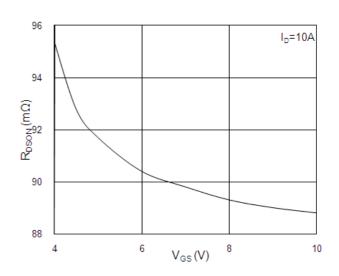


Fig.2 On-Resistance vs. Gate-Source

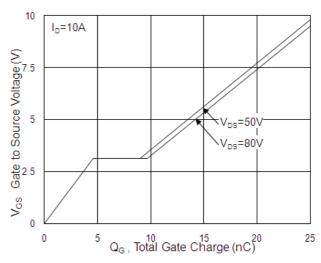


Fig.4 Gate-Charge Characteristics

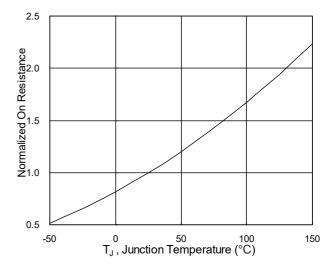
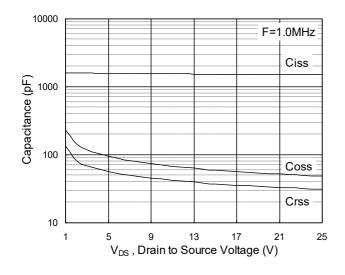


Fig.6 Normalized R_{DSON} vs. T_J





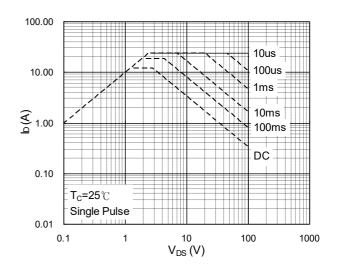


Fig.7 Capacitance

Fig.8 Safe Operating Area

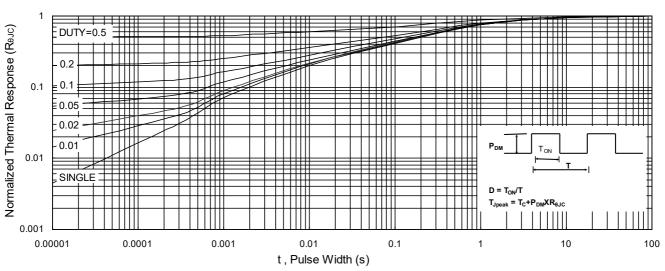


Fig.9 Normalized Maximum Transient Thermal Impedance

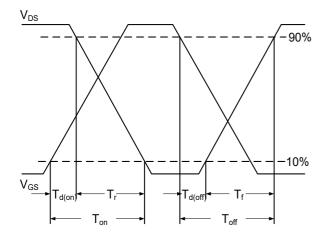


Fig.10 Switching Time Waveform

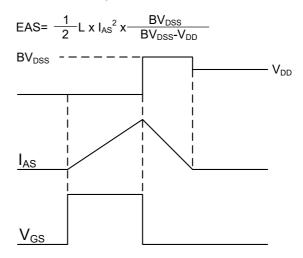
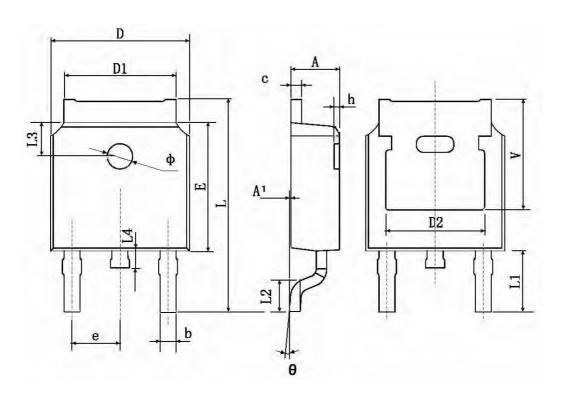


Fig.11 Unclamped Inductive Switching Waveform

TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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